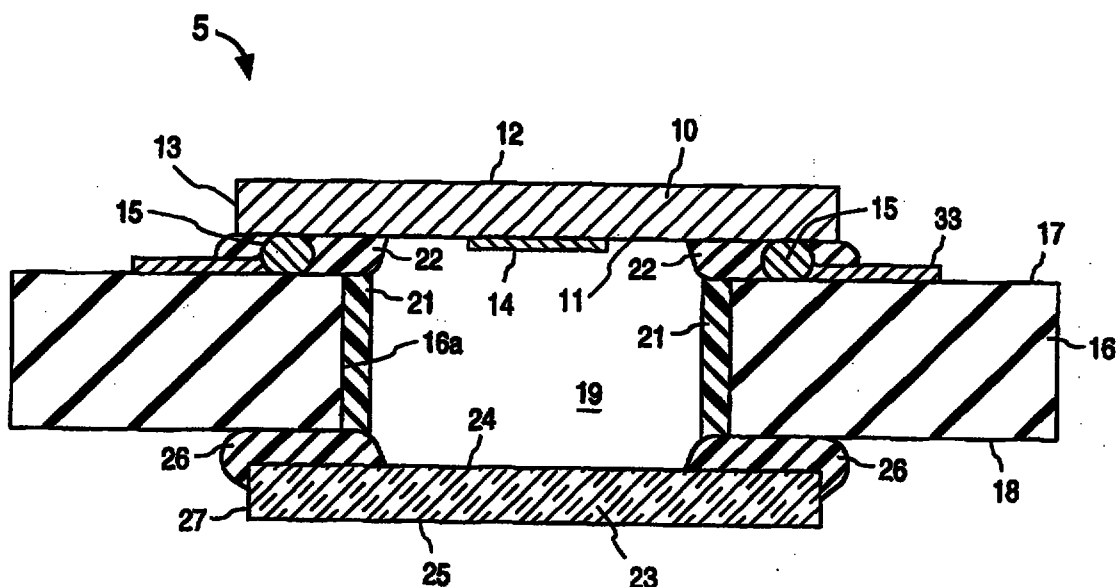




INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : H01L 31/0203, G11C 16/06, H01L 23/28		A1	(11) International Publication Number: WO 99/13516
			(43) International Publication Date: 18 March 1999 (18.03.99)
(21) International Application Number: PCT/US98/18003 (22) International Filing Date: 8 September 1998 (08.09.98) (30) Priority Data: 08/926,495 9 September 1997 (09.09.97) US 09/118,197 17 July 1998 (17.07.98) US (71) Applicant: AMKOR TECHNOLOGY, INC. [US/US]; 1900 South Price Road, Chandler, AZ 85248-1604 (US). (72) Inventor: GLENN, Thomas, P.; 1001 South Crown Key Court, Gilbert, AZ 85233 (US). (74) Agents: PARSONS, James, E. et al.; Skjerven, Morrill, MacPherson, Franklin & Friel LLP, Suite 700, 25 Metro Drive, San Jose, CA 95110 (US).			(81) Designated States: CA, JP, KR, SG, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>

(54) Title: MOUNTING HAVING AN APERTURE COVER WITH ADHESIVE LOCKING FEATURE FOR FLIP CHIP OPTICAL INTEGRATED CIRCUIT DEVICE



(57) Abstract

A mounting for a flip chip integrated circuit device having a light sensitive cell is disclosed. The mounting includes an insulating substrate having an aperture between its first and second surfaces. A flip chip integrated circuit device is placed on the first surface of the substrate. A light sensitive cell of the integrated circuit device faces the aperture. Solder bumps on the integrated circuit are electrically connected to corresponding conductive metallizations on the first surface of the substrate. A transparent aperture cover is affixed to the second surface of the substrate with an adhesive bead. The aperture cover extends over the aperture, allowing light to be transmitted through the aperture cover to the light sensitive cell. The side surfaces of the aperture cover include features for locking the adhesive bead to the aperture cover. The numerous locking features disclosed include protrusions and indentations that engage the adhesive bead and thereby enhance the connection of the aperture cover to the substrate.